2SA1617

Silicon PNP Epitaxial

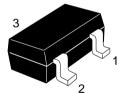
HITACHI

Application

High voltage amplifier

Outline

MPAK



- 1. Emitter
- 2. Base
- 3. Collector



2SA1617

Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

| Item | Symbol | Ratings | Unit |
|------------------------------|------------------|-------------|------|
| Collector to base voltage | V_{CBO} | – 55 | V |
| Collector to emitter voltage | V_{CEO} | – 50 | V |
| Emitter to base voltage | V_{EBO} | - 5 | V |
| Collector current | I _c | -100 | mA |
| Collector power dissipation | P _c | 150 | mW |
| Junction temperature | Tj | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

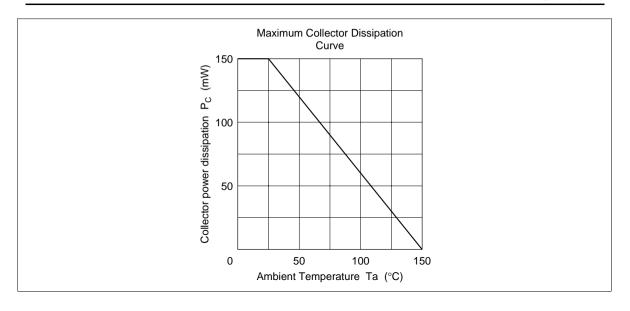
Electrical Characteristics (Ta = 25°C)

| Item | Symbol | Min | Тур | Max | Unit | Test conditions |
|---|----------------------|-------------|-----|------|------|---|
| Collector to base breakdown voltage | $V_{(BR)CBO}$ | – 55 | _ | _ | V | $I_{c} = -10 \ \mu A, \ I_{E} = 0$ |
| Collector to emitter breakdown voltage | $V_{(BR)CEO}$ | -50 | _ | _ | V | $I_C = -1 \text{ mA}, R_{BE} = \infty$ |
| Emitter to base breakdown voltage | $V_{(BR)EBO}$ | - 5 | _ | _ | V | $I_{E} = -10 \ \mu A, \ I_{C} = 0$ |
| Collector cutoff current | I _{CBO} | _ | _ | -0.5 | μΑ | $V_{CB} = -30 \text{ V}, I_{E} = 0$ |
| Emitter cutoff current | I _{EBO} | _ | _ | -0.5 | μΑ | $V_{EB} = -2 \text{ V}, I_{C} = 0$ |
| DC current transfer ratio | h _{FE} *1 | 100 | _ | 320 | | $V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$ |
| Collector to emitter saturation voltage | $V_{\text{CE(sat)}}$ | _ | _ | -0.2 | V | $I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -1 \text{ mA}$ |
| Base to emitter voltage | V_{BE} | _ | _ | -0.8 | V | $V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$ |

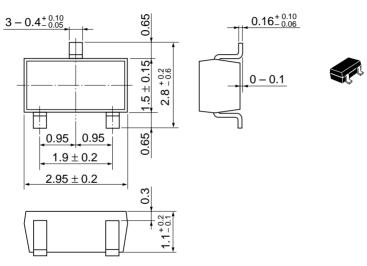
Note: 1. The 2SA1617 is grouped by h_{FE} as follows.

| Grade | В | С | |
|-----------------|------------|------------|--|
| Mark | VIB | VIC | |
| h _{FE} | 100 to 200 | 160 to 320 | |

See charcteristic curves of 2SA1031



Unit: mm



| Hitachi Code | MPAK |
|--------------------------|----------|
| JEDEC | _ |
| EIAJ | Conforms |
| Weight (reference value) | 0.011 g |

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